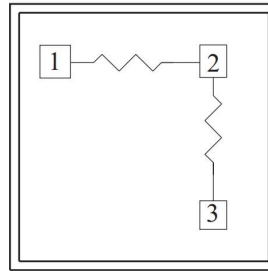


### Features

- Withstand high current
- Small size
- One chip can be with different resistances
- Can customize according to requirements

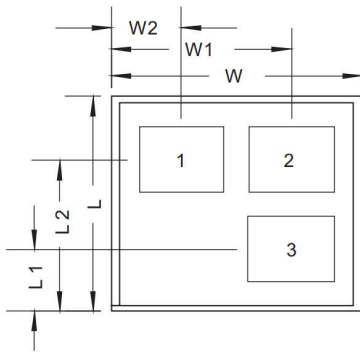
### Function Diagram



### Electrical Specifications (Ta=+25°C, 50Ω system)

Part Number	W	W1	W2	L	L1	L2	Standard Resistance (Ω)		
	mm	mm	mm	mm	mm	mm	1→2	2→3	1→3
BW517	0.45	0.32	0.12	0.5	0.14	0.36	4	8	12
BW518	0.45	0.32	0.12	0.5	0.14	0.36	5	10	15
BW519	0.48	0.36	0.12	0.58	0.14	0.44	20	40	60

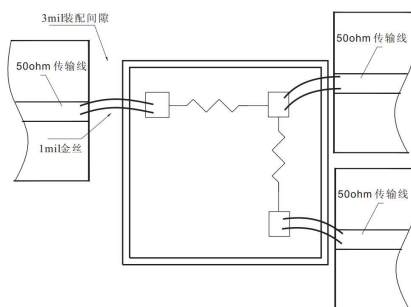
### Outline Size



### Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated,  
Pad size: 200\*100(um), 100\*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Application



### Absolute Rating

Max. Handling current	150mA
Junction Temperature	175°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

### Bonding Pads Definition

Number	Symbol	Description
1、2、3	In, Out	Any two ports can be used as input or output
	GND	Bottom must be grounded